

AMENDMENTS TO THE CLAIMS:

Please cancel claim 13, without prejudice or disclaimer of its subject matter, and add new claims 14-16, as indicated below. This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (Original) A semiconductor device, comprising:

a wiring board;

a semiconductor chip provided on said wiring board and having a pad electrically connected to a wiring on said wiring board; and

a second semiconductor chip provided on said wiring board at a position facing a side of said semiconductor chip, having passive elements integrated therein, and having pads for external connection to which both ends of the passive elements are connected respectively and at least one of which is electrically connected to the wiring on said wiring board electrically connected to the pad of said semiconductor chip.

2. (Original) A semiconductor device as set forth in claim 1, wherein the passive elements integrated in said second semiconductor chip are elements of one kind, or two kinds or more selected from a group of a capacitor, a resistor, and an inductor.

3. (Original) A semiconductor device as set forth in claim 1, wherein said semiconductor chip is flipchip-connected to said wiring board so as to electrically connect the pad to the wiring on said wiring board.

4. (Original) A semiconductor device as set forth in claim 1, wherein said semiconductor chip has bonding wire connection to the wiring of said wiring board so as to electrically connect the pad to the wiring on said wiring board.

5. (Original) A semiconductor device as set forth in claim 1, wherein said second semiconductor chip is flipchip-connected to said wiring board so as to electrically connect the pads for external connection to the wiring on said wiring board.

6. (Original) A semiconductor device as set forth in claim 1, wherein said second semiconductor chip has bonding wire connection to the wiring of said wiring board so as to electrically connect the pads for external connection to the wiring on said wiring board.

7. (Original) A semiconductor device as set forth in claim 1, wherein said semiconductor chip and said second semiconductor chip are both 60 μm or less in thickness.

8. (Original) A semiconductor device as set forth in claim 5, wherein said second semiconductor chip has, besides the pads for external connection used for the flipchip connection to said wiring board, a pad for external connection not contributing to the flipchip connection to said wiring board.

9. (Original) A semiconductor device, comprising:

a plurality of semiconductor device portion units arranged in a lamination direction and each including: a wiring board; a semiconductor chip provided on said wiring board and having a pad electrically connected to a wiring on said wiring board; and a second semiconductor chip provided on said wiring board at a position facing a side of said semiconductor chip, having passive elements integrated therein, and having pads for external connection to which both ends of the passive elements are connected respectively and at least one of which is electrically connected to the wiring on said wiring board electrically connected to the pad of said semiconductor chip; and

a vertical wiring portion passing through said wiring boards of said plural semiconductor device portion units and electrically connecting said wiring boards to one another.

10. (Original) A semiconductor device as set forth in claim 9, wherein the passive elements integrated in said second semiconductor chips of the respective plural semiconductor device portion units are elements of one kind, or two kinds or more selected from a group of a capacitor, a resistor, and an inductor.

11. (Original) A semiconductor package member, comprising:

a wiring board on which a semiconductor chip is mountable; and

an auxiliary semiconductor chip provided on said wiring board at a position facing a side of said semiconductor chip to be mounted, having passive elements integrated therein, and

having pads for external connection to which both ends of the passive elements are connected respectively and at least one of which is electrically connected to a wiring on said wiring board.

12. (Original) A semiconductor package member as set forth in claim 11, wherein the passive elements integrated in said auxiliary semiconductor chips are elements of one kind, or two kinds or more selected from a group of a capacitor, a resistor, and an inductor.

13. (Cancelled)

14. (New) A semiconductor device as set forth in claim 1, wherein each of the pads of said second semiconductor chip electrically connected to the pad of said semiconductor chip is positioned to be adjacent to said pad of said semiconductor chip.

15. (New) A semiconductor device as set forth in claim 9, wherein in each of the plurality of semiconductor device portion units each of the pads of said second semiconductor chip electrically connected to the pad of said semiconductor chip is positioned to be adjacent to said pad of said semiconductor chip.

16. (New) A semiconductor package member as set forth in claim 11, wherein each of the pads of said auxiliary semiconductor chip electrically connected to the wiring on said wiring board is positioned to be adjacent to a pad of said semiconductor chip to be mounted, the pad being to be connected to said wiring.